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July 2013

# FSA2269 / FSA2269TS — Low-Voltage Dual-SPDT (0.4 $\Omega$ ) Analog Switch with Negative Swing Audio Capability

### **Features**

- 0.4 Ω Typical On Resistance (R<sub>ON</sub>) for +3.0 V Supply
- 0.25 Ω Maximum R<sub>ON</sub> Flatness for +3.0 V Supply
- -3 db Bandwidth: > 50 MHz
- Low-I<sub>CCT</sub> Current Over an Expanded Control Input Range
- Packaged in 10-Lead MicroPak™, UMLP, and WLCSP
- Power-Off Protection on Common Ports
- Broad V<sub>CC</sub> Operating Range: 1.65 to 4.5 V
- Noise Immunity Termination Resistors in FSA2269TS

# **Applications**

- Cell Phone, PDA, Digital Camera, and Notebook
- LCD Monitor, TV, and Set-Top Box

# **Description**

The FSA2269 is a high-performance, dual Single-Pole Double-Throw (SPDT) analog switch with negative swing audio capability. The FSA2269 features ultra-low  $R_{ON}$  of 0.4  $\Omega$  (typical) at 3.0 V V $_{\rm CC}$ . The FSA2269 operates over a wide V $_{\rm CC}$  range of 1.65 V to 4.5 V, is fabricated with sub-micron CMOS technology to achieve fast switching speeds, and is designed for break-before-make operation. The select input is TTL-level compatible.

The FSA2269 features very low quiescent current even when the control voltage is lower than the  $V_{\rm CC}$  supply. This feature suits mobile handset applications by allowing direct interface with baseband processor general-purpose I/Os with minimal battery consumption.

The FSA2269TS includes termination resistors that improve noise immunity during overshoot excursions, off-isolation coupling, or "pop-minimization."

# **Ordering Information**

Part Number	Top Mark	Package Description				
FSA2269L10X	HL	10-Lead, MicroPak, JEDEC MO-255, 1.6 x 2.1 mm				
FSA2269UMX	HP	0-Lead, Quad Ultrathin Molded Leadless Package (UMLP), 1.4 x 1.8 mm, 0.4 mm Pitch				
FSA2269TSL10X	HU	10-Lead, MicroPak, JEDEC MO-255, 1.6 x 2.1 mm				
FSA2269TSUMX HT 10-Lead, Quad Ultrathin Molded Leadless Package(UMLP), 1.4 x 1.8 mm, 0.4 mm Pitch						
FSA2269UCX	N9	12-Ball, Wafer-Level Chip Scale Package (WLCSP),1.2 x 1.6 mm, 0.4 mm Pitch				

# **Analog Symbols**

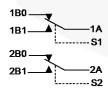


Figure 1. FSA2269

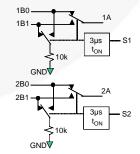


Figure 2. FS A2269TS (with Slow Turn On)

# **Pin Configuration**

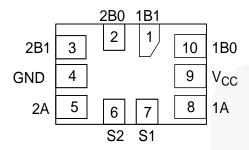


Figure 3. 10-Pin UMLP (Top Through View)

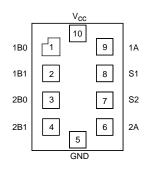


Figure 4. 10-Pin MicroPak™ (Top Through View)

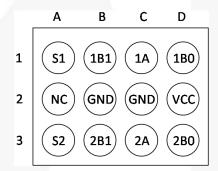


Figure 5. 12-Ball WLCSP (Bump Side View)

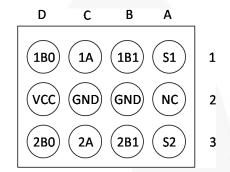


Figure 6. 12-Ball WLCSP (Top Side View)

# **Pin Descriptions**

Pin # UMLP	Pin # Micropak	WLCSP	Name	Description		
1	2	B1	1B1	Data Ports		
2	3	D3	2B0	Data Ports		
3	4	В3	2B1	Data Ports		
4	5	B2, C2	GND	Ground		
5	6	C3	2A	Data Ports		
6	7	A3	S2	Switch Select Pins		
7	8	A1	S1	Switch Select Pins		
8	9	C1	1A	Data Ports		
9	10	D2	Vcc	Supply Voltage		
10	1	D1	1B0	Data Ports		

# **Truth Table**

Control Input, Sn	Function
LOW Logic Level	nB0 connected to nA (FSA2269/2269TS); nB1 terminated to GND (FSA2269TS only)
HIGH Logic Level	nB1 connected to nA (FSA2269/2269TS); nB0 terminated to GND (FSA2269TS only)

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. Functional operation above the recommended operating conditions is not implied. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. Absolute maximum ratings are stress ratings only.

Symbol		Parameter			Min.	Max.	Unit
Vcc	Supply Voltage					5.5	V
Vsw	Switch I/O Voltage <sup>(1)</sup>	1B0, 1B1, 2B0, 2B	31, 1A, 2	A Pins	V <sub>CC</sub> -4.6	5.5	V
V <sub>CNTRL</sub>	Control Input Voltage <sup>(1)</sup>	S1, S2			-0.5	V <sub>CC</sub> +0.3	V
Isw	Switch I/O Current (Continu	ious)				350	mA
ISWPEAK	Peak Switch Current	Pulsed at 1ms Du	ration, <	10% Duty Cycle		500	mΑ
T <sub>STG</sub>	Storage Temperature Range			-65	+150	°C	
TJ	Maximum Junction Temperature				+150	°C	
T <sub>L</sub>	Lead Temperature		Solderi	ing, 10 Seconds		+260	°C
MSL	Moisture Sensitivity Level, C	JEDEC J-STD-020	Á	7/1		1	
1/			I/O to C	GND		12	
1	Human Body Model, JEDE	C: JESD22-A114	I/O to GND FSA2269UCX			11	
ESD				to GND		8	kV
	All Other Pins			er Pins		7	
A	Charged Device Model, JE	DEC: JESD22-C10	1			2	

#### Note:

1. Input and output negative ratings may be exceeded if input and output diode current ratings are observed.

# **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Unit
Vcc	Supply Voltage <sup>(2)</sup>	1.65	4.50	V
V <sub>S1, S2</sub>	Control Input Voltage	0V	Vcc	V
V <sub>SW</sub>	Switch I/O Voltage	V <sub>CC</sub> -4.3	Vcc	V
T <sub>A</sub>	Operating Temperature	-40	+85	°C

### Note:

2. For 4.5 V operation, SEL frequency (pins S1 & S2) should not exceed 100 Hz and 50 ns edge rate.

# **DC Electrical Characteristics**

All typical values are T<sub>A</sub>=25°C unless otherwise specified.

Symbol	Parameter	arameter Conditions		Т	T <sub>A</sub> =+25°C			T <sub>A</sub> =-40 to +85°C		
				Min.	Тур.	Max.	Min.	Max.		
			3.60 to 4.50				1.70			
			3.00 to 3.60				1.50			
$V_{\text{IH}}$	Input Voltage High		2.70 to 3.00				1.35		.,	
			2.30 to 2.70				1.30		v	
			1.65 to 1.95				0.90			
			3.60 to 4.50					0.7	V	
\/	Input Valtage Levy		2.70 to 3.60					0.5		
VIL	Input Voltage Low		2.30 to 2.70					0.4	V	
			1.65 to 1.95		Á			0.4		
I <sub>IN</sub>	Control Input Leakage (S1, S2)	V <sub>IN</sub> =0 to V <sub>CC</sub>	1.65 to 4.50		4		-0.5	0.5	μA	
I <sub>NO(0FF)</sub> , I <sub>NC(0FF)</sub>	Off Leakage Current of Port nB0 and nB1 (FSA2269 only)	nA=0.5 V, V <sub>CC</sub> =0.5 V nB0 or nB1=V <sub>CC</sub> - 0.5 V, 0.5 V, or Floating Figure 8	1.95 to 4.50	-50		50	-250	250	nA	
I <sub>A(ON)</sub>	On Leakage Current of Port nA	nA=0.5 V, V <sub>CC</sub> -0.5 V nB0 or nB1=V <sub>CC</sub> - 0.5 V, 0.5 V, or Floating Figure 9	1.95 to 4.50	-20		20	-150	150	nA	
l	Power-Off Leakage Current (Common Port Only 1 A, 2A) (FSA2269)	Common Port (1A, 2A), V <sub>IN</sub> =0 V to 4.5 V, V <sub>CC</sub> =0V nB0, nB1=Floating	0					±1	μA	
l <sub>OFF</sub>	Power-Off Leakage Current (Common Port Only 1 A, 2A) (FSA2269TS)	Common Port (1A, 2A), V <sub>IN</sub> =0V to 4.5 V, V <sub>CC</sub> =0 V nB0, nB1=0 V or Floating	0			A		±45	μA	
		I <sub>ON</sub> =100 mA, nB0 or nB1=0.7 V, 3.6 V, 4.5 V, Figure 7	4.50		0.30			1		
D	Switch On	I <sub>ON</sub> =100 mA, nB0 or nB1=0.7 V, 3.6 V, Figure 7	3.00		0.40		1	0.80	0	
R <sub>ON</sub>	Resistance <sup>(3,6)</sup>	I <sub>ON</sub> =100mA, nB0 or nB1=0V, 0.7 V, 1.6 V, 2.3 V, Figure 7	2.30		0.52			(F	Ω	
		I <sub>ON</sub> =100 mA, nB0 or nB1=0V, 0.7 V, 1.65 V, Figure 7	1.65		1.00					
			4.50		0.04			0.13		
۸D	On Resistance	I <sub>ON</sub> =100 mA, nB0 or	3.00		0.06			0.13	_	
$\Delta R_{ON}$	Matching Between Channels (4)	nB1=0.7 V	2.30		0.12				Ω	
			1.65		1.00					

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# DC Electrical Characteristics (Continued)

All typical values are T<sub>A</sub>=25°C unless otherwise specified.

Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> =+25°C			T <sub>A</sub> =-4	Unit		
				Min.	Тур.	Max.	Min.	Max.		
			4.50					0.25		
D	On Resistance	I <sub>OUT</sub> =100 mA, nB0 or nB1=0V to V <sub>CC</sub>	3.00					0.25	Ω	
R <sub>FLAT(ON)</sub>	Flatness (5)		2.30		0.5					
			1.65		0.6					
R <sub>TERM</sub>	Internal Termination Resistors <sup>(6)</sup> (FSA2269TS only)				10				kΩ	
Icc	Quiescent Supply Current	V <sub>IN</sub> =0 or V <sub>CC</sub> , I <sub>OUT</sub> =0	4.50	-100		100	-500	500	nA	
loor	Increase in I <sub>CC</sub> per	Input at 2.6 V	4.50		3.0			10.0		
Ісст	Input	Input at 1.8 V	4.30		7.0			15.0	μA	

### Notes:

- On resistance is determined by the voltage drop between A and B pins at the indicated current through the switch.
- 4.  $\Delta$  R<sub>ON</sub>=R<sub>ON max</sub> R<sub>ON min</sub> measured at identical V<sub>CC</sub>, temperature, and voltage.
- 5. Flatness is defined as the difference between the maximum and minimum value of on resistance (R<sub>ON</sub>) over the specified range of conditions.
- 6. Guaranteed by characterization, not production tested.

# **AC Electrical Characteristics**

All typical value are T<sub>A</sub>=25°C unless otherwise specified.

0	Danamatan	. Conditions	V 00	T,	<sub>A</sub> =+25 <sup>0</sup>	C	T <sub>A</sub> =-40	to +85°C	1111	F:	
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	Min.	Тур.	Max.	Min.	Max.	Unit	Figure	
		DO	3.60 to 4.50			55	15	60			
	Turn-On Time	nB0 or nB1=1.5 V,	2.70 to 3.60			60	15	65		Figure 10	
	FSA2269	R <sub>L</sub> =50 Ω,	2.30 to 2.70			100	15	110	ns	Figure 11	
		C <sub>L</sub> =35 pF	1.65 to 1.95		70						
		nB0 or	3.60 to 4.50			105	15	110			
	Turn-On Time	nB1=1.5 V,	2.70 to 3.60			115	15	150		Figure 10	
ton	FSA2269UCX	$R_L=50 \Omega$ ,	2.30 to 2.70			180	15	185	ns	Figure 11	
		C <sub>L</sub> =35 pF	1.65 to 1.95		110						
	<i>X</i>	nB0 or	3.60 to 4.50			3.5	0.5	4.0			
	Turn-On Time	nB1=1.5 V,	2.70 to 3.60			4.5	0.5	5.0		Figure 10	
	FSA2269TS	R <sub>L</sub> =50 Ω, C <sub>L</sub> =35 pF	2.30 to 2.70			6.0	0.5	7.0	μs	Figure 11	
		CL=35 pF	1.65 to 1.95		8.0						
	V	nB0 or	3.60 to 4.50			50	5	55			
	Turn-Off Time	nB1=1.5 V,	2.70 to 3.60			55	5	60	ns	Figure 10	
	FSA2269	R <sub>L</sub> =50 Ω,	2.30 to 2.70			60	5	65		Figure 11	
		C <sub>L</sub> =35 pF	1.65 to 1.95		40						
			nB0 or	3.60 to 4.50			100	5	105		
4	Turn-Off Time	n-Off Time nB1=1.5 V,	2.70 to 3.60			110	5	115	200	Figure 10 Figure 11	
toff	FSA2269UCX	R <sub>L</sub> =50 Ω,	2.30 to 2.70			120	5	125	ns		
		C <sub>L</sub> =35 pF	1.65 to 1.95		80						
		nB0 or	3.60 to 4.50			45	5	50			
	Turn-Off Time	nB1=1.5 V,	2.70 to 3.60			50	5	55		Figure 10	
	FSA2269TS	R <sub>L</sub> =50 Ω,	2.30 to 2.70			55	5	60	ns	Figure 11	
		C <sub>L</sub> =35 pF	1.65 to 1.95		50		-	/			
7		nB0 or	3.60 to 4.50		3		1				
•	Break-Before- Make Time	nB1=1.5 V,	2.70 to 3.60		5		2		no	Figure 12	
t <sub>BBM</sub>	FSA2269 <sup>(7)</sup>	$R_L=50 \Omega$	2.30 to 2.70		10		2		ns	rigure 12	
	Y	C <sub>L</sub> =35 pF	1.65 to 1.95		5		2				
	1	nB0 or	3.60 to 4.50		9.5		5.5				
4	Break-Before- Make Time	nB1=1.5 V,	2.70 to 3.60		17.0		15.0		no	Figure 12	
t <sub>BBM</sub>	FSA2269UCX <sup>(7)</sup>	$R_{L}=50 \Omega$	2.30 to 2.70		22.0		20.0		ns	Figure 12	
		C <sub>L</sub> =35 pF	1.65 to 1.95		46.0		41.0				
		nB0 or	3.60 to 4.50		1.5		1.0				
tore	Break-Before- Make Time	nB1=1.5 V,	2.70 to 3.60		3.0		1.5			Figure 40	
t <sub>BBM</sub>	FSA2269TS <sup>(7)</sup>	$R_L=50 \Omega$ ,	2.30 to 2.70		4.0		2.5		μS	Figure 12	
		C <sub>L</sub> =35 pF	1.65 to 1.95		5.0		3.0				

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# **AC Electrical Characteristics** (Continued)

All typical value are  $T_A=25^{\circ}C$  unless otherwise specified.

Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	Т	+25º	С	T <sub>A</sub> =-4 +85		Unit	Figure
				Min.	Тур.	Max.	Min.	Max.		
Q	Charge Injection	$C_L$ =1.0 nF, $V_S$ =0 V, $R_S$ =0 $\Omega$	1.65 to 4.50		25				pC	Figure 16
OIRR	Off Isolation	f=100 kHz, R <sub>L</sub> =50 Ω, C <sub>L</sub> =0 pF	1.65 to 4.50		-70				dB	Figure 14
Xtalk	Crosstalk	f=100 kHz, R <sub>L</sub> =50 Ω, C <sub>L</sub> =0 pF	1.65 to 4.50		-70		À		dB	Figure 15
BW	-3db Bandwidth	R <sub>L</sub> =50 Ω, C <sub>L</sub> =0 pF	1.65 to 4.50		>50				MHz	Figure 13
THD	Total Harmonic Distortion	$\begin{array}{l} \text{f=20 Hz to} \\ \text{20 kHz,} \\ \text{R}_{\text{L}}\text{=}32~\Omega, \\ \text{V}_{\text{IN}}\text{=}2~\text{V}_{\text{PP}} \\ \text{V}_{\text{BIAS}}\text{=}0~\text{V} \end{array}$	1.65 to 4.50		.06				%	Figure 19

#### Notes

7. Guaranteed by characterization, not production tested.

# Capacitance

Symbol	Symbol Parameter		Parameter Conditions		V <sub>CC</sub> (V)	-	T <sub>A</sub> =+25°	С	Unit	Figure
Symbol	raiailletei	Conditions	VCC (V)	Min.	Тур.	Max.	riguie			
C <sub>IN</sub>	Control Pin Input Capacitance	f=1 MHz	0		2.5	l.	pF	Figure 17		
C <sub>OFF</sub>	B Port Off Capacitance	f=1 MHz	3.3		30		pF	Figure 17		
Con	A Port On Capacitance	f=1 MHz	3.3		120		pF	Figure 18		

# **Test Diagrams**

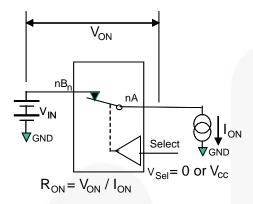
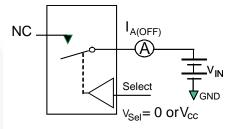


Figure 7. On Resistance



\*\*Each switch port is tested separately.

Figure 8. Off Leakage

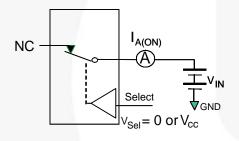


Figure 9. On Leakage

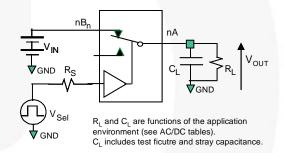


Figure 10. Test Circuit Load

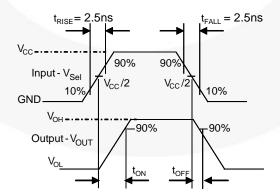


Figure 11. Turn-On / Turn-Off Waveforms

# Test Diagrams (Continued)

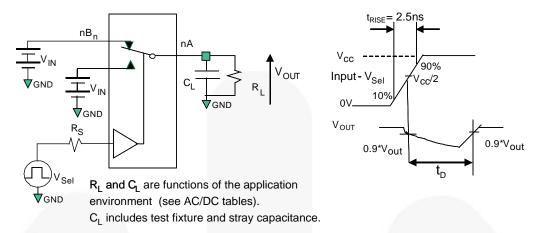


Figure 12. Break-Before-Make Interval Timing

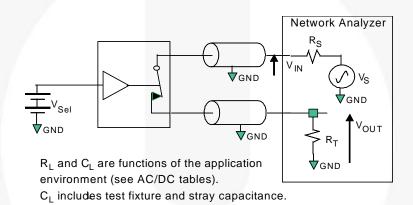


Figure 13. Bandwidth

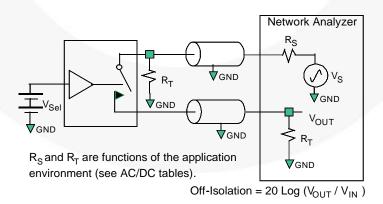


Figure 14. Channel Off Isolation

# Test Diagrams (Continued)

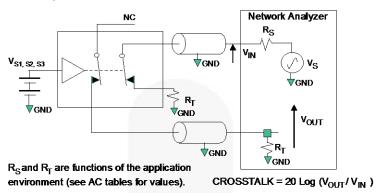


Figure 15. Adjacent Channel Crosstalk

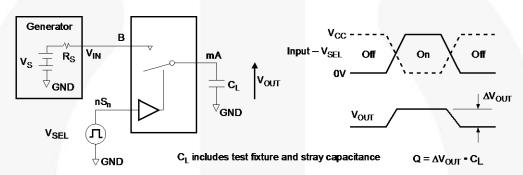


Figure 16. Charge Injection Test

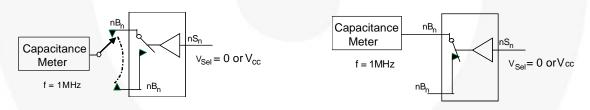


Figure 17. Channel Off Capacitance

Figure 18. Channel On Capacitance

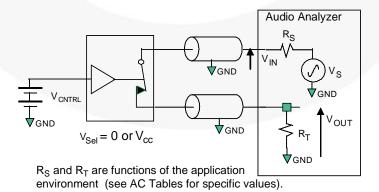


Figure 19. Total Harmonic Distortion

# **Physical Dimensions**

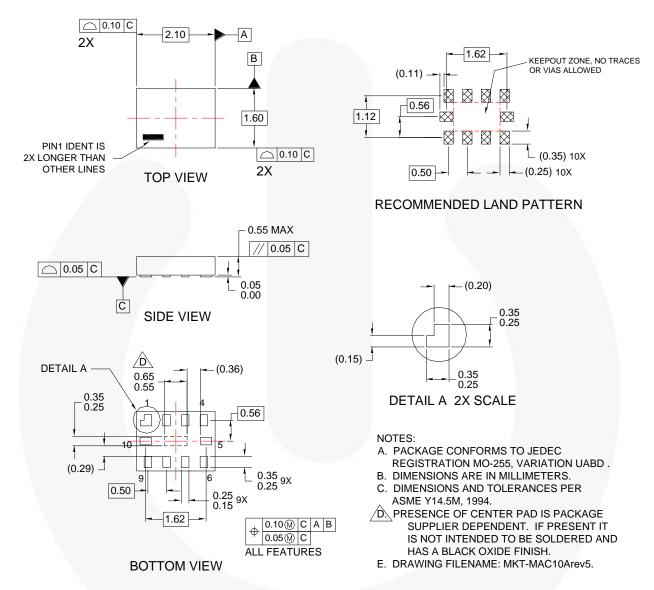


Figure 20. 10-Lead MicroPak™

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

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# Physical Dimensions (Continued)

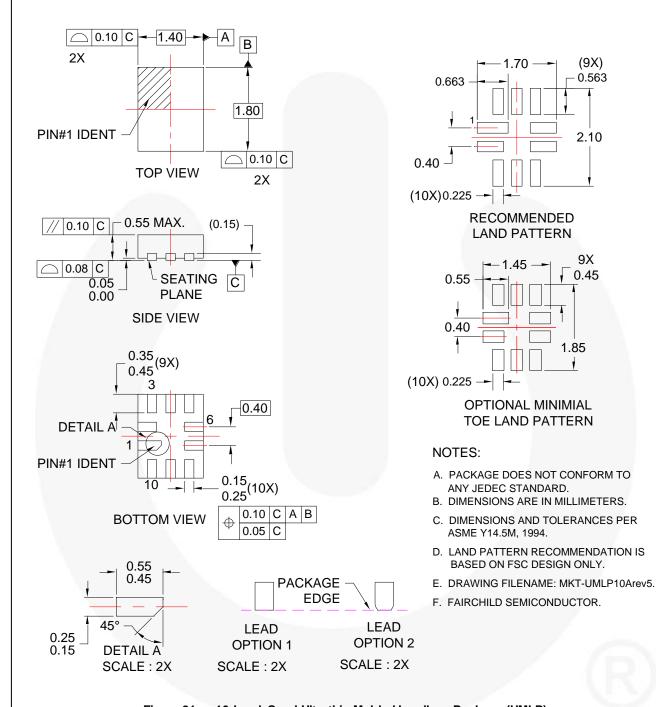
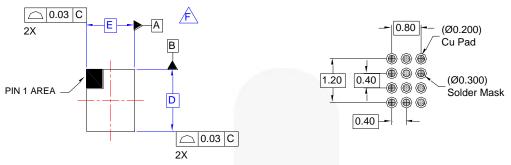


Figure 21. 10-Lead, Quad Ultrathin Molded Leadless Package (UMLP)

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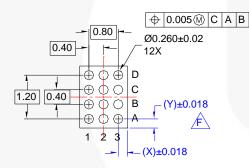
# Physical Dimensions (Continued)



TOP VIEW







**BOTTOM VIEW** 

### NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).

F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

G. DRAWING FILENAME: MKT-UC012ACrev1.

### **Product-Specific Dimensions**

Product	D	E	X	Υ
FSA2269UCX	1.560 mm	1.160 mm	0.180 mm	0.180 mm

Figure 22. 12-Ball, Wafer Level Chip-Scale Package (WLCSP)

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Rev. 164

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